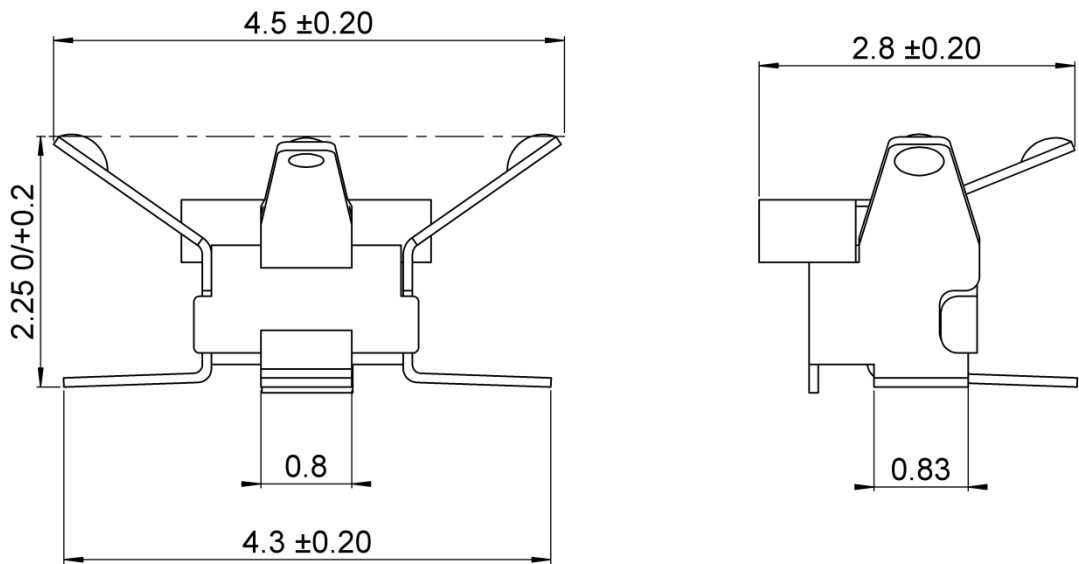
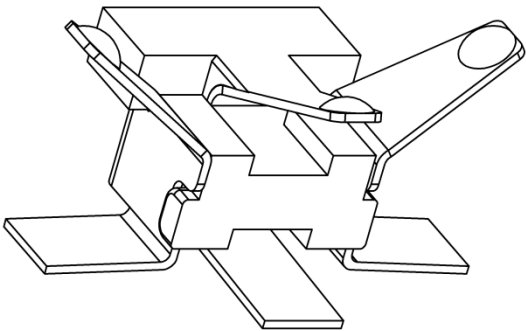


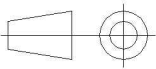
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Scale : 1/1



All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (μm)
Body	BERYLLIUM COPPER	GOLD OVER NICKEL
Center contact	BERYLLIUM COPPER	GOLD OVER NICKEL
Outer contact	BERYLLIUM COPPER	GOLD OVER NICKEL
Insulator	POLYETHER ETHERCETONE 30% GF	
Gasket		
Others parts		
-	-	-
-	-	-

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PACKAGING

Standard	Unit	Other
3500	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω
Frequency		0-6	GHz
VSWR	1.5	+	0 x F(GHz) Maxi
Insertion loss		0.3	√F(GHz) dB Maxi
RF leakage	- (NA	- F(GHz) dB Maxi
Voltage rating		100	Veff Maxi
Dielectric withstanding voltage		350	Veff mini
Insulation resistance		3000	MΩ mini

ENVIRONMENTAL

Operating temperature	-40/+90	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	NA	N mini
Axial force – Opposite end	NA	N mini
Torque	NA	N.cm mini

Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm

Mating life	10	Cycles mini
Nominal Weight	0,013	g
(Add +15% for max weight)		

SPECIFICATION

OTHER CHARACTERISTICS

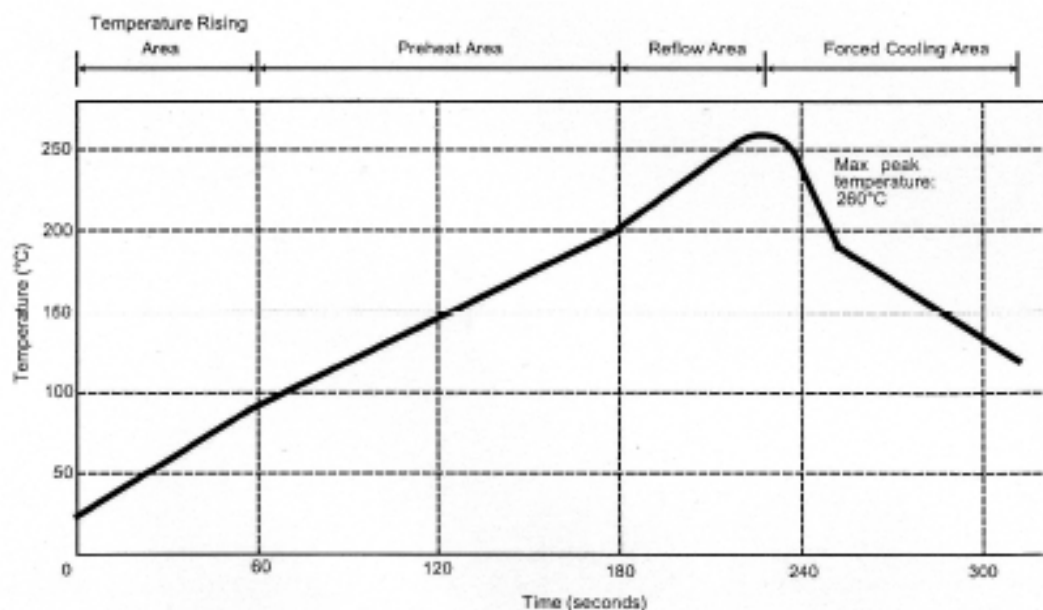
Assembly instruction: **NA**

Others:

SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven.
Below please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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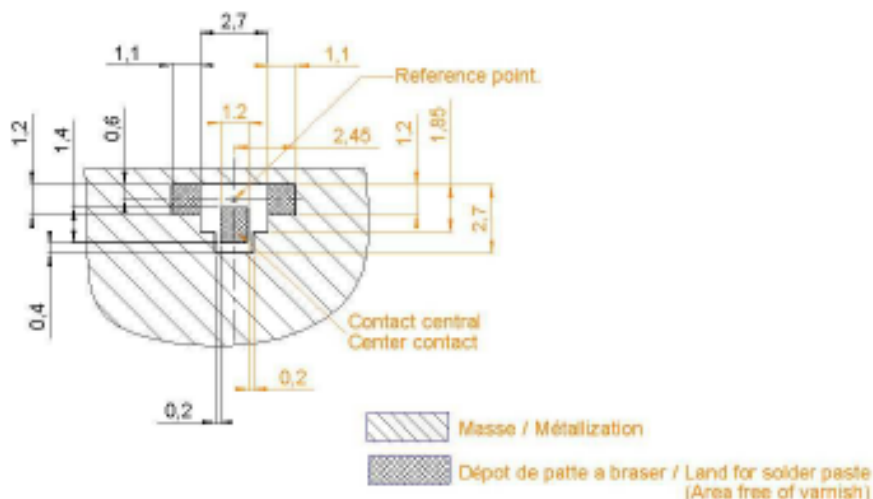
SERIES **IMP**

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IMP SERIES INFORMATION

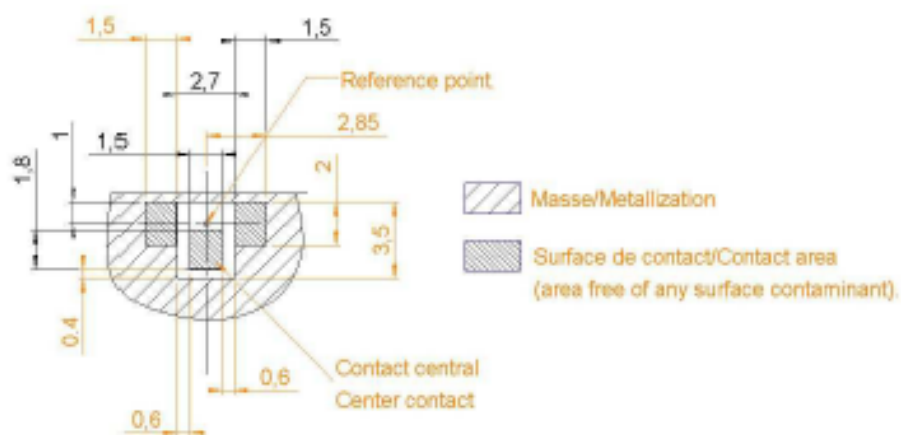
All dimension are in mm

PCB 1



Vias and transmission line inside PCB are not represented.
The impedance of the transmission line should be 50 ohms

PCB 2



Vias and transmission line inside PCB are not represented.
The impedance of the transmission line should be 50 ohms

RADIAL MISALIGNMENT IN MM : 0.2 IN INCH : .008

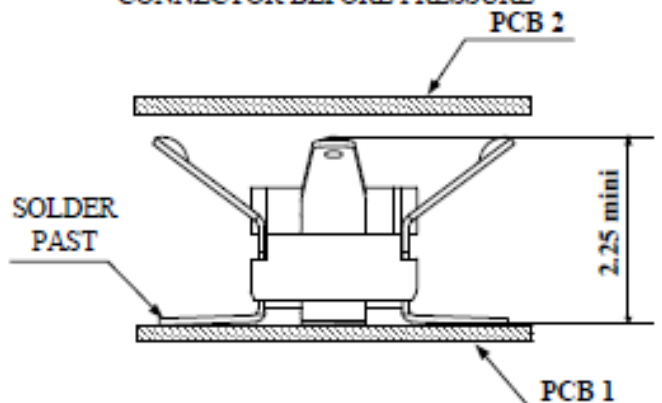
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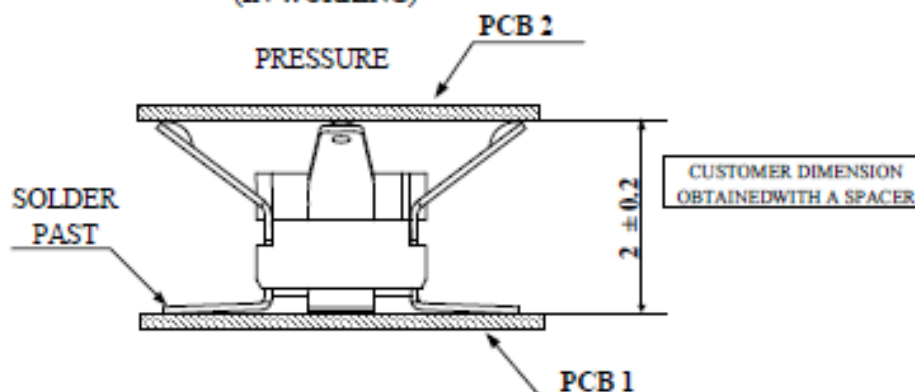
SERIES IMP

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IMP-SERIES-INFORMATION
CONNECTOR BEFORE PRESSURE



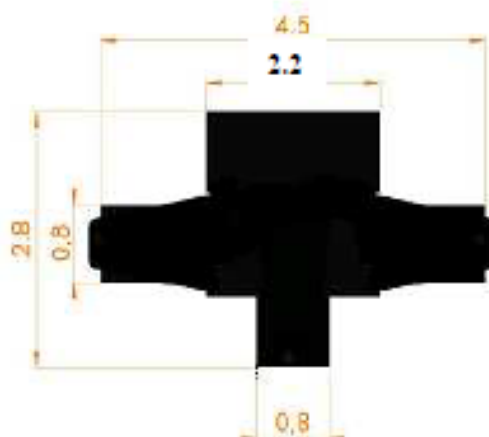
CONNECTOR IN PRESSURE
(IN WORKING)



THE CONNECTOR IS NOT A SPACER, SO THE 2 ± 0.2 DIMENSION A MUST BE ENSURED WITH AN ADDED PIECE. PART SETTED 10 mm MAX. FAR FROM THE IMP CONNECTOR.

Shadow of IMP receptacle
for video camera.

All dimensions are in mm.



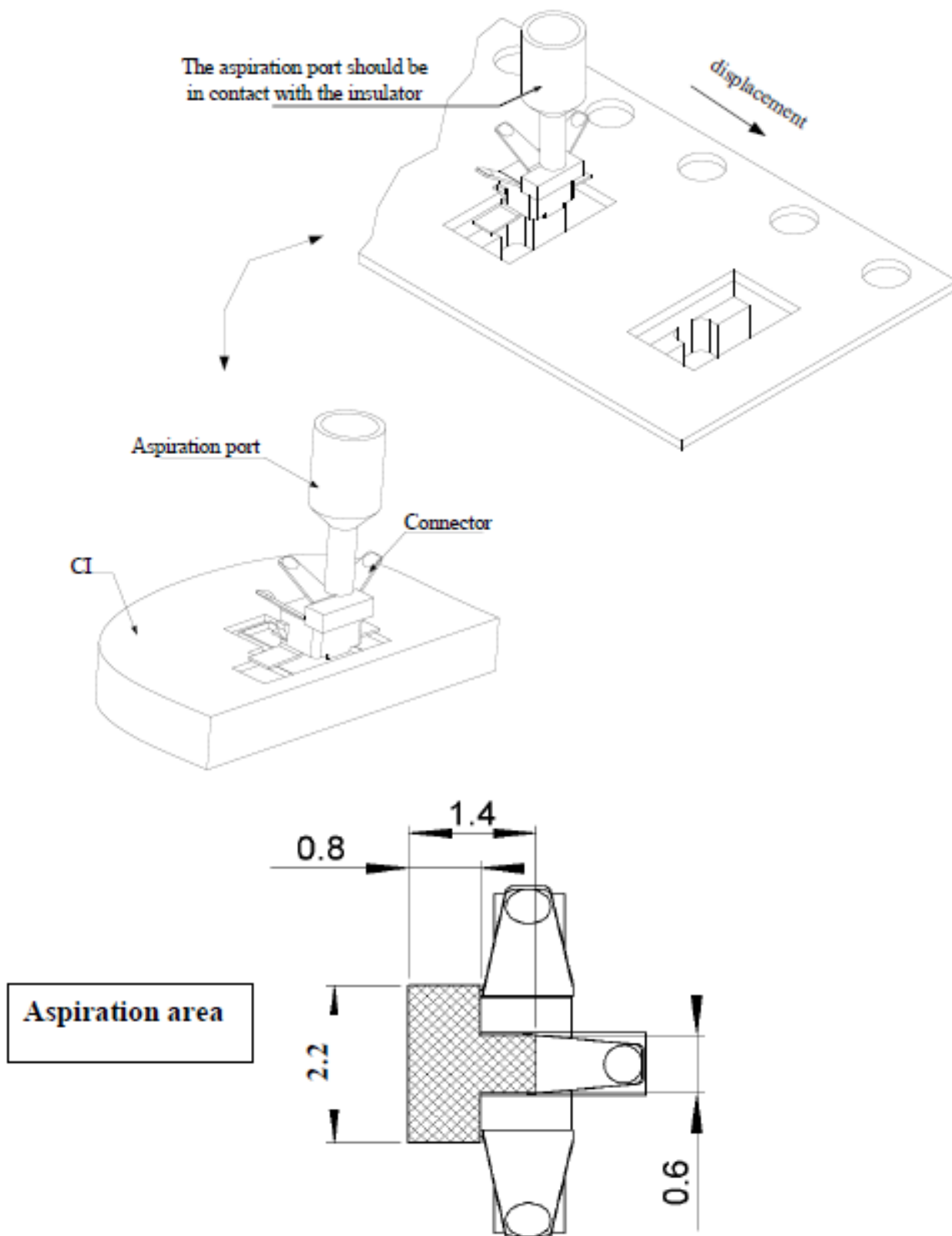
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IMP-SERIES-Information



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